

Amendments to the Claims

1-22.(cancelled)

23.(currently amended) A semiconductor chip package, comprising:
a semiconductor chip having a first surface and a second surface ~~perpendicular-~~
~~to and~~ intersecting the first surface;
conductive leads electrically connected to and extending along the first surface
of the chip at least to the intersection of the first and second surfaces;
a continuous body of encapsulating material substantially encapsulating the chip
and the conductive leads; and
solder balls each having a first portion disposed in the encapsulating material
and contacting a conductive lead and a second portion protruding from the
encapsulating material.

24.(currently amended) A semiconductor chip package, comprising:
a semiconductor chip having a first surface and a second surface ~~perpendicular-~~
~~to and~~ intersecting the first surface and bond pads aligned along the first surface of the
chip;
~~insulating material on the surface of the chip, the insulating material having holes~~
~~therein to enable electrical connection to the bond pads;~~
conductive leads ~~attached to the insulating material, each lead~~ electrically
connected to the bond pads and each lead extending along the first surface of the chip
at least to the intersection of the first and second surfaces;
a continuous body of encapsulating material, ~~discrete from the insulating~~
~~material,~~ substantially encapsulating the chip and the conductive leads; and
solder balls each having a first portion disposed in the encapsulating material
and contacting a conductive lead and a second portion protruding from the
encapsulating material.